ON Semiconductor®

Initial Product/Process Change Notification

Document #:IPCN23253X
Issue Date:02 Apr 2020

Title of Change:	Qualify UTAC as additional Assembly and Test site for FDMF5062.
Proposed First Ship date:	09 Aug 2020 or earlier if approved by customer
Contact Information:	Contact your local ON Semiconductor Sales Office or Ravi.Savanur@onsemi.com
PCN Samples Contact:	Contact your local ON Semiconductor Sales Office or PCN.samples@onsemi.com Sample requests are to be submitted no later than 30 days from the date of first notification, Initial PCN or Final PCN, for this change. Samples delivery timing will be subject to request date, sample quantity and special customer packing/label requirements.
Type of Notification:	This is an Initial Product/Process Change Notification (IPCN) sent to customers. An IPCN is an advance notification about an upcoming change and contains general information regarding the change details and devices affected. It also contains the preliminary reliability qualification plan.The completed qualification and characterization data will be included in the Final Product/Process Change Notification (FPCN). This IPCN notification will be followed by a Final Product/Process Change Notification (FPCN) at least 90 days prior to implementation of the change. In case of questions, contact PCN.Support@onsemi.com
Marking of Parts/ Traceability of Change:	The Marking will have site information for tracebility
Change Category:	Assembly Change, Test Change
Change Sub-Category(s):	Manufacturing Site Addition

Sites Affected:

ON Semiconductor Sites	**External Foundry/Subcon Sites**
None	UTAC, Thailand

Description and Purpose:

To increase capacity, UTAC - Thailand is being qualified as additional Assembly and Test site of 5x6 QFN products.

	Before Change Description	**After Change Description**
Assembly and Test Site	ON Semiconductor – Cebu, Philippines	ON Semiconductor – Cebu, Philippines UTAC - Thailand

The parts can be identified by the data code used, which has location information encoded.

There are no product material changes as a result of this change.

There is no product marking change as a result of this change.

Qualification Plan:

QV DEVICE NAME: FDMF3009
RMS : F62703 & W62702
PACKAGE : PQFN39 CU 3DIE HPBF

Test	Specification	Condition	Interval
HTOL	JESD22-A108	Ta=125°C, 100 % max rated Vcc	1008 hrs
HTSL	JESD22-A103	Ta= 150°C	1008 hrs
TC	JESD22-A104	Ta= -65°C to +150°C	500 cyc
HAST	JESD22-A110	130°C, 85% RH, 18.8psig, bias	192 hrs
uHAST	JESD22-A118	130°C, 85% RH, 18.8psig, unbiased	96 hrs
PC	J-STD-020 JESD-A113	MSL-1 @ 260°C	
RSH	JESD22- B106	Ta = 265C, 10 sec	

Estimated date for qualification completion: 10 April 2020

List of Affected Parts:

***Note:** Only the standard (off the shelf) part numbers are listed in the parts list. Any custom parts affected by this PCN are shown in the customer specific PCN addendum in the PCN email notification, or on the **PCN Customized Portal**.*

Part Number	Qualification Vehicle
FDMF5062	FDMF3009